

SKIU-SUB INTEL® 4TH GEN. HASWELL ® CORETM

17-4700EQ MIL-STD FANLESS RUGGED System



Extended Tem	perature
+70°C	-40°C

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- MIL-STD 810G COMPLIANCE
- 4TH GENERATION INTEL[®] Core[™]
 17-4700EQ Haswell Processor
- XR-DIMM UP TO 8 GB RAM
- ONBOARD USSD SATAIII UP TO 64 GB
- 2 X MPCIE EXPANSION SLOT (ONE CO-LAYOUT WITH MSATA)
- 2 x PCIE INTEL® GIGABIT ETHERNET
- 4 x USB 3.0, 1 x COM PORT
- 9V TO 36V DC-IN WITH POWER DELAY ON/OFF





SPECIFICATIONS

SYSTEM		
CPU	Intel® Core™ i7 Haswell , BGA type Core i7-4700EQ (4C x 2.4/1.7 GHz), 6M Cache (47W	
Chipset	Intel® QM87 PCH	
Ethernet Chipset	Intel® I210IT & i217-LM GbE	
Memory	1 x DDR3 1600 XR-DIMM up to 8 GB with ECC	
Expansion Slot	2 x mPCle (1 x colay with mSATA)	
Storage Device	Onboard uSSD SATAIII up to 64 GB	
FRONT I/O		
Power Button	Power Button with dual color LED backlight	
Power LED	1 x Green LED	
HDD LED	1 x Red LED	
LAN LED	2 x Red LED, 2 Green LED	
USB	2 x USB 3.0	
REAR I/D		
Power	1 x Terminal Block	
Ethernet	2 x RJ45	
COM	1 x RS232/422/485 with 5V/12V selectable	
USB	2 x USB 3.0	
DVI-I	1 (Default CLOSED)	
DisplayPort	2	
Audio	1 x MIC, 1 x Line out	
MECHANICAL & ENVI	RONMENT	
Power Requirements	9V to 36V DC-in, AT/ATX mode sup-ports with power delay on/off	
Dimension(W xH x D)	308 x 149 x 59 mm	
Weight	3.05kg(6.72lbs)	
Operating Temp.	-40 to 70°C (ambient with air flow)	
Storage Temp.	-40 to 85°C	
Relative Humidity	5% to 95%, non-condensing	



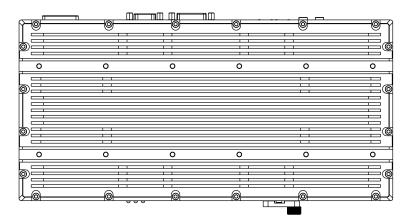


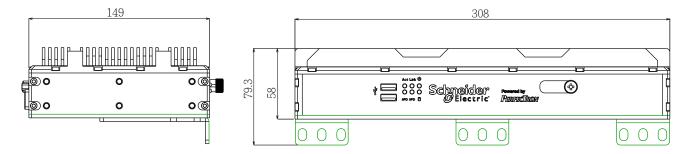
SERIAL INTERFACE & SIGNALS	
Serial Standards	1x RS-232/422/485 port, Jumper-se-lectable (DB9 male)
RS-232	TxD, RxD, DTR, DSR, RTS, CTS, DCD, GND
RS-422	TxD+, TxD-, RxD+, RxD-, GND
RS-485-4w	TxD+, TxD-, RxD+, RxD-, GND
RS-485-2w	Data+, Data-, GND
STANDARDS AND C	GERTIFICATIONS
	Method 507.5, Procedure II (Temperature & Humidity)
	Method 514.6, Procedure I (Category 20 & 24, Vibration)
	Method 516.6, Procedure I (Mechanical Shock)
MIL-STD-810G Test	Method 501.5, Procedure I (Storage/High
	Temperature) Method 501.5, Procedure II (Operation/
	High Temperature) Method 502.5, Procedure I
	(Storage/Low Temperature) Method 502.5,
	Procedure II (Operation/Low Temperature) Method
	503.5, Procedure I (Temperature shock)
EMC	CE and FCC compliance
Green Product	RoHS, WEEE compliance





APPEARANCE





ORDERING

SR10-SCH

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INTEL® QM87 MIL-STD FANLESS RUGGED SYSTEM WITH INTEL® CORE 17-4700EQ HASWELL PROCESSOR, 9V TO 36V DC-IN, WIDE TEMP -40 TO 70° C

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